

# INN150LA070A

## 1. General description

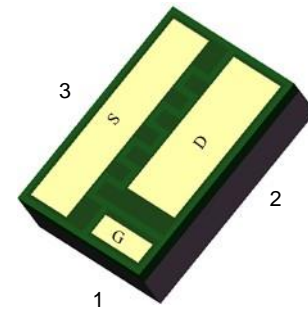
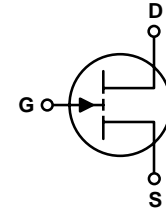
GaN-on-Silicon enhancement mode high-electron-mobility-transistor (HEMT) in Flip chip LGA (FCLGA) with 3.2 mm x 2.2 mm package size.

## 2. Features

- GaN-on-Silicon E-mode HEMT technology
- Very low gate charge
- Ultra-low on resistance
- Very small package size
- Zero reverse recovery charge

## 3. Applications

- Synchronous rectification
- Class-D audio
- High frequency DC-DC converter
- Communication base station
- Motor driver



## 4. Key performance parameters

**Table 1** Key performance parameters at  $T_J = 25\text{ }^\circ\text{C}$

Parameter	Value	Unit
$V_{DS,max}$	150	V
$R_{DS(on),max}$ @ $V_{GS} = 5\text{ V}$	7	m $\Omega$
$Q_{G,typ}$ @ $V_{DS} = 85\text{ V}$	7.6	nC
$I_{DS,Continuous}$	28	A
$Q_{OSS}$ @ $V_{DS} = 85\text{ V}$	47	nC

## 5. Pin information

**Table 2** Pin information

PIN	Pin Description	Pin Function
1	Gate	Driver Gate
2	Drain	Power Drain
3	Source	Power Source

**Table 3** Ordering information

Type/Ordering Code	Package	Product Code
INN150LA070A	LGA 3.2x2.2	M01

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## 6. Maximum ratings

at  $T_J = 25\text{ °C}$  unless otherwise specified.

Continuous application of maximum ratings can deteriorate transistor lifetime. For further information, contact Innoscience sales office.

**Table 4** Maximum ratings

SYMBOL	PARAMETER	MAX	UNIT
$V_{DS}$	Drain-to-Source Voltage (Continuous)	150	V
$I_D$	Continuous current	28	A
	Pulsed ( $25\text{ °C}$ , $T_{Pulse} = 300\ \mu\text{s}$ )	120	A
$V_{GS}$	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	V
$T_J$	Operating Temperature	-40 to 150	$\text{°C}$
$T_{STG}$	Storage Temperature	-40 to 150	$\text{°C}$

## 7. Thermal characteristics

**Table 5 Thermal characteristics**

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>TYP</b>	<b>UNIT</b>
$R_{\theta JC}$	Thermal Resistance, Junction to Case	26	$^{\circ}\text{C}/\text{W}$
$R_{\theta JB}$	Thermal Resistance, Junction to Board	4.4	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>1</sup>	57	$^{\circ}\text{C}/\text{W}$

Note 1:  $R_{\theta JA}$  is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.

## 8. Electric characteristics

at  $T_J = 25\text{ }^\circ\text{C}$ , unless specified otherwise

**Table 6** Static characteristics

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	TEST CONDITIONS
$BV_{DSS}$	Drain-to-Source Voltage	150	-	-	V	$V_{GS} = 0\text{ V}$ , $I_D = 900\text{ }\mu\text{A}$
$I_{DSS}$	Drain Source Leakage	-	8	45	$\mu\text{A}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = 120\text{ V}$
$I_{GSS}$	Gate-to-Source Forward Leakage	-	1	32	$\mu\text{A}$	$V_{GS} = 5\text{ V}$
	Gate-to-Source Reverse Leakage	-	8	45	$\mu\text{A}$	$V_{GS} = -4\text{ V}$
$V_{GS(TH)}$	Gate Threshold Voltage	0.8	1.1	2.1	V	$V_{DS} = V_{GS}$ , $I_D = 5\text{ mA}$
$R_{DS(on)}$	Drain-Source On-state Resistance	-	5.6	7	$\text{m}\Omega$	$V_{GS} = 5\text{ V}$ , $I_D = 10\text{ A}$
$V_{SD}$	Source-Drain Forward Voltage	-	1.2	-	V	$I_S = 0.5\text{ A}$ , $V_{GS} = 0\text{ V}$

**Table 7 Dynamic characteristics**

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	TEST CONDITIONS
$C_{iss}$	Input Capacitance	-	865	-	pF	$V_{GS} = 0\text{ V}, V_{DS} = 85\text{ V}$
$C_{oss}$	Output Capacitance	-	280	-		$V_{GS} = 0\text{ V}, V_{DS} = 85\text{ V}$
$C_{rss}$	Reverse Transfer Capacitance	-	2.5	-		$V_{GS} = 0\text{ V}, V_{DS} = 85\text{ V}$
$C_{oss(er)}$	Energy Related $C_{oss}$	-	380	-		$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 85\text{ V}$
$C_{oss(tr)}$	Time Related $C_{oss}$	-	555	-		$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 85\text{ V}$
$R_G$	Gate resistance	-	2.3	-	$\Omega$	$f = 5\text{ MHz}, \text{ drain open}$
$Q_G$	Total Gate Charge	-	7.6	-	nC	$V_{GS} = 5\text{ V}, V_{DS} = 85\text{ V}, I_D = 10\text{ A}$
$Q_{GS}$	Gate to Source Charge	-	1.7	-		$V_{DS} = 0\text{ V to } 85\text{ V}, I_D = 10\text{ A}$
$Q_{GD}$	Gate to Drain Charge	-	1.3	-		$V_{DS} = 0\text{ V to } 85\text{ V}, I_D = 10\text{ A}$
$Q_{G(TH)}$	Gate Charge at Threshold	-	1.3	-		$V_{DS} = 0\text{ V to } 85\text{ V}, I_D = 10\text{ A}$
$Q_{oss}$	Output Charge	-	47	-		$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 85\text{ V}$

## 9. Electric characteristics diagrams

at  $T_J = 25^\circ\text{C}$ , unless specified otherwise

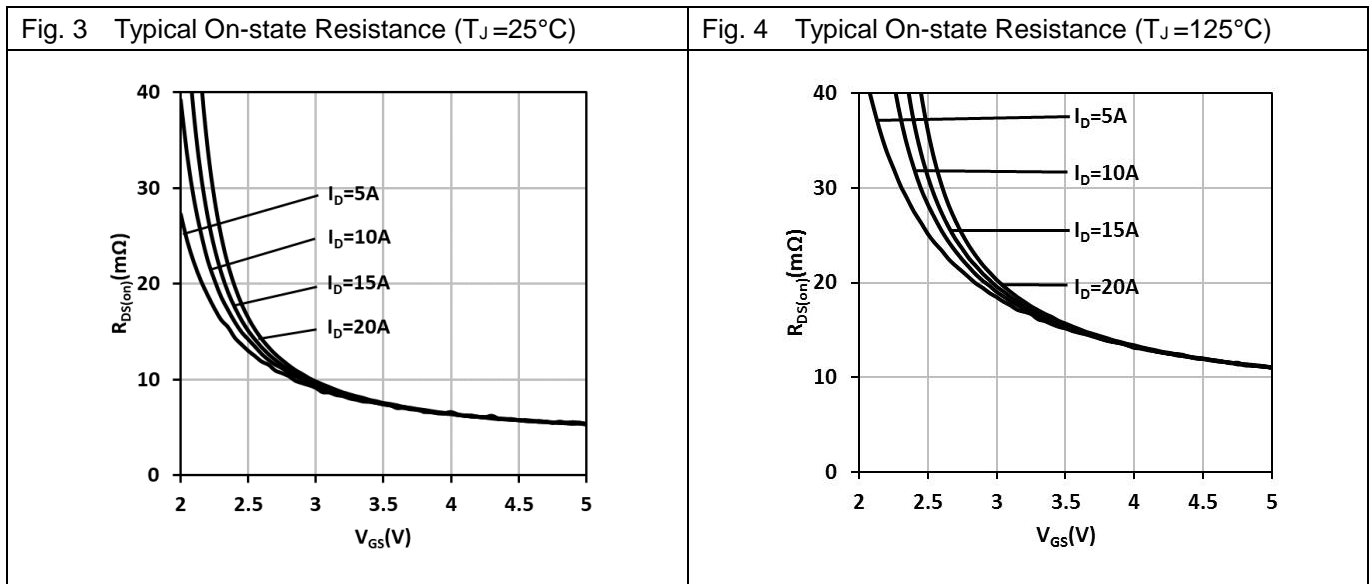
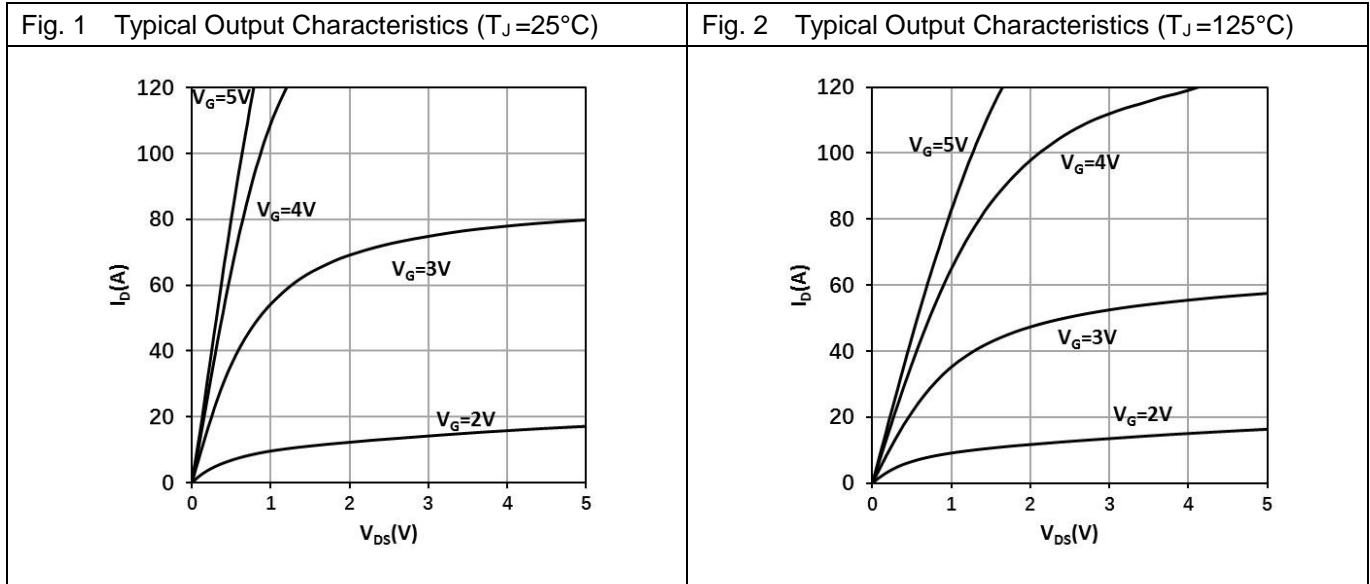


Fig. 5 Normalized On-State Resistance vs. Temp.

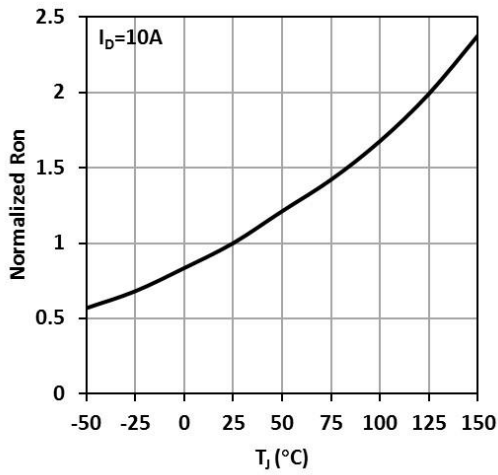


Fig. 6 Typical Transfer Characteristics

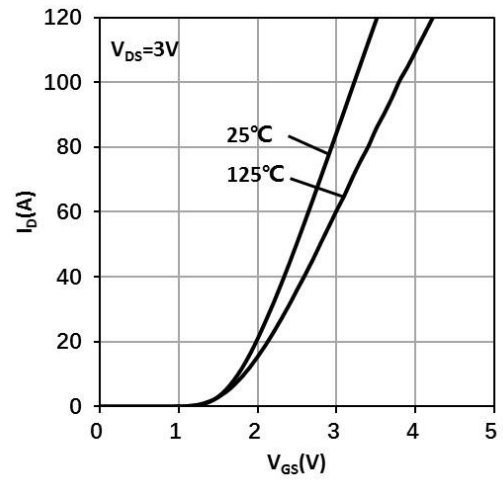


Fig. 7 Typ. Reverse Characteristics ( $V_{GS} \leq 0, T_J = 25^\circ\text{C}$ )

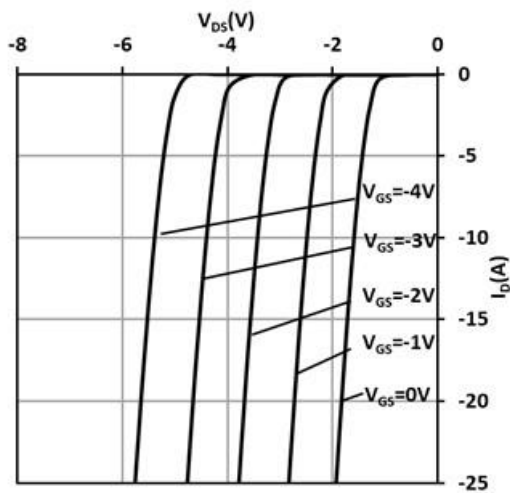


Fig. 8 Typ. Reverse Characteristics ( $V_{GS} \geq 0, T_J = 25^\circ\text{C}$ )

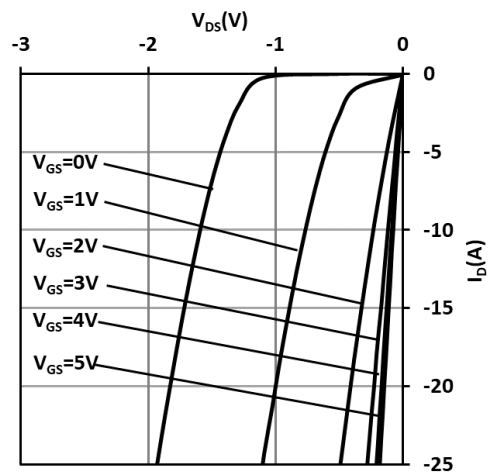




Fig. 9 Typ. Reverse Characteristics  
( $V_{GS} \leq 0, T_J = 125^\circ\text{C}$ )

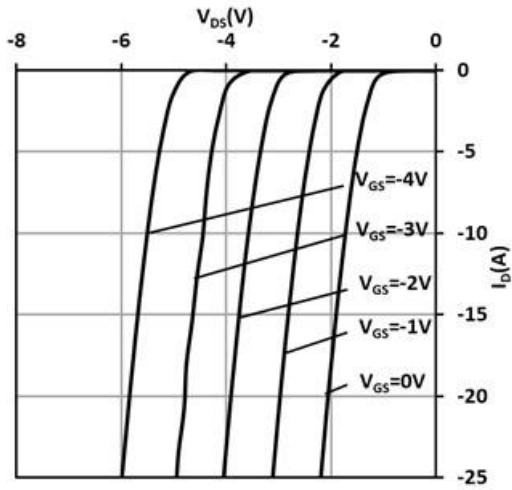


Fig. 10 Typ. Reverse Characteristics  
( $V_{GS} \geq 0, T_J = 125^\circ\text{C}$ )

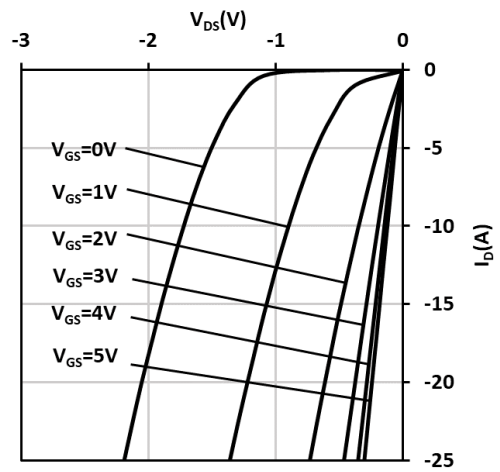


Fig. 11 Typ. Capacitances Characteristics

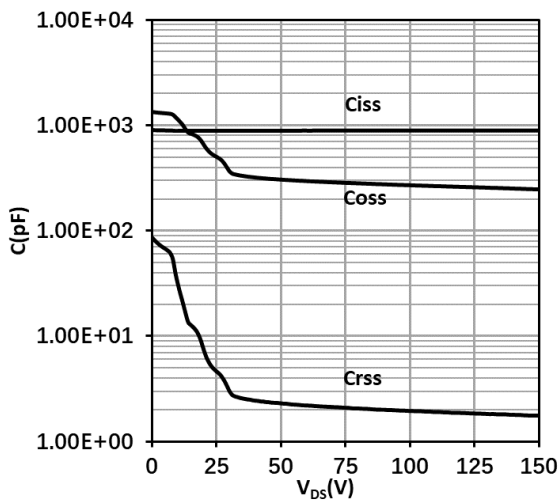


Fig. 12 Typ. Gate Charge

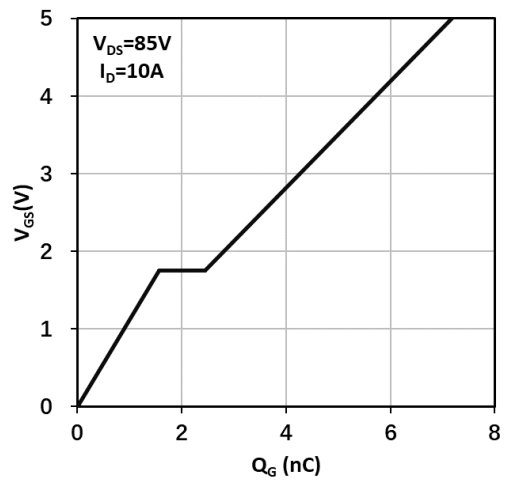


Fig. 13 Normalized Threshold Voltage vs. Temp.

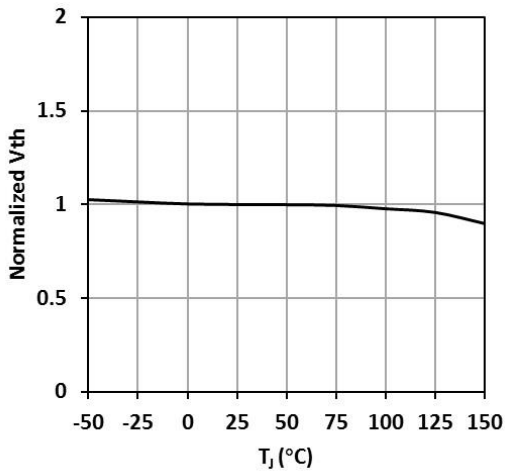


Fig. 14 Output Charge

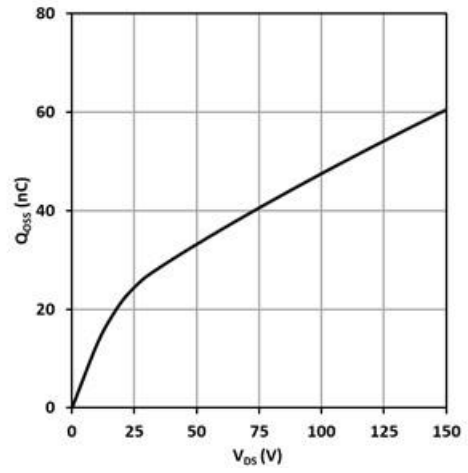


Fig. 15 Output Capacitance Stored Energy

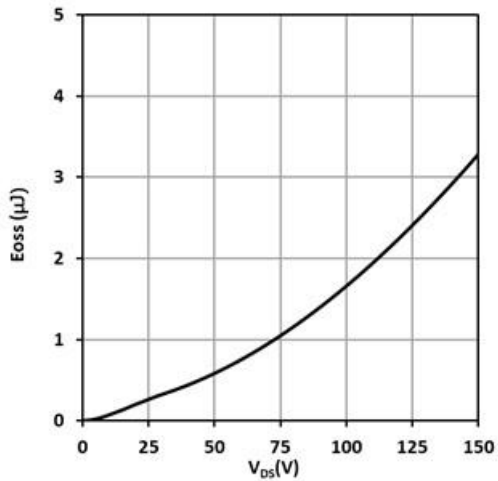


Fig. 16 Power Dissipation

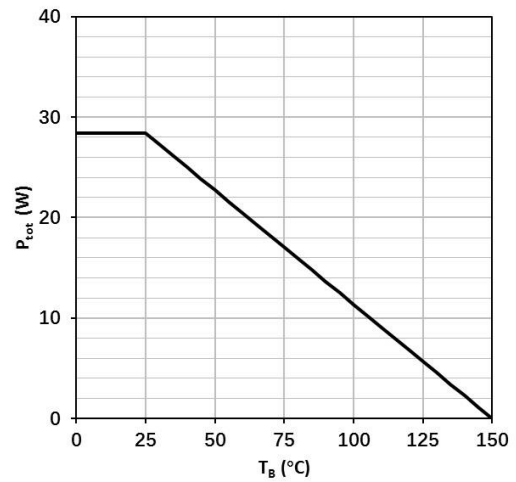


Fig. 17 Safe Operating Area

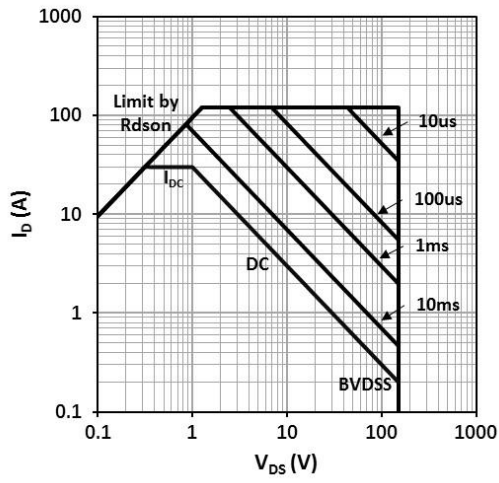
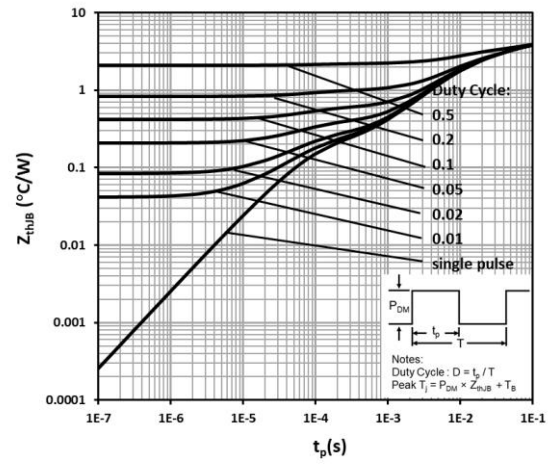
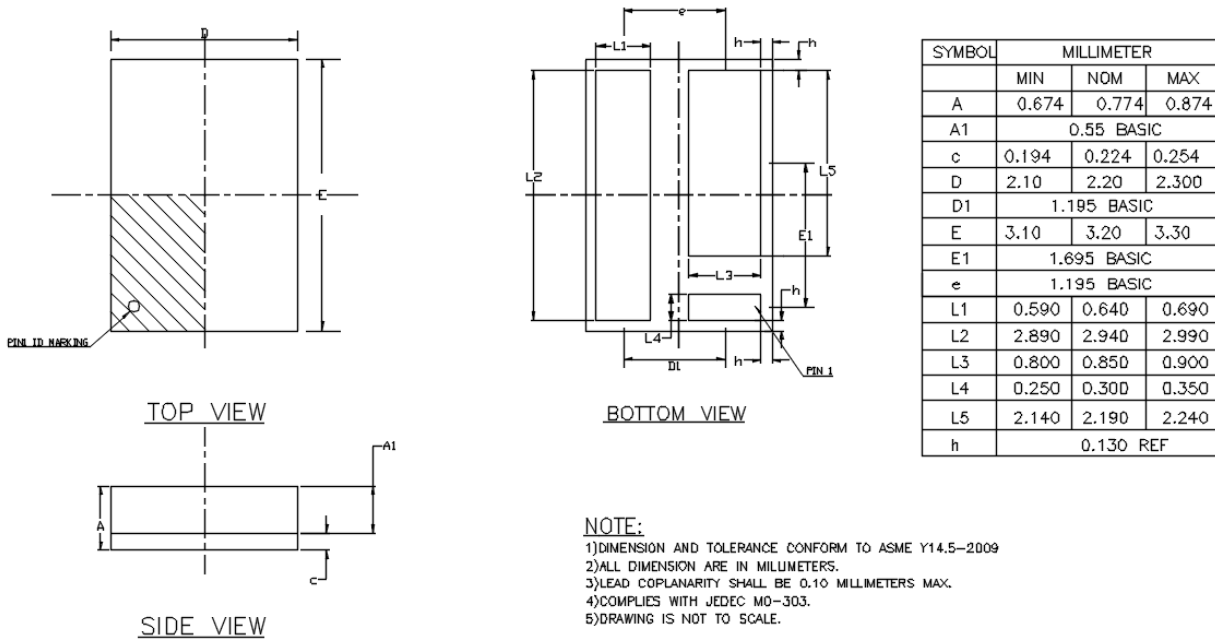


Fig. 18 Max. Transient Thermal Impedance

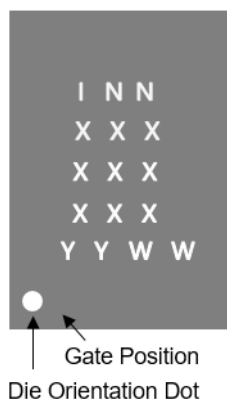


## 10. Package outlines

### Package Reference

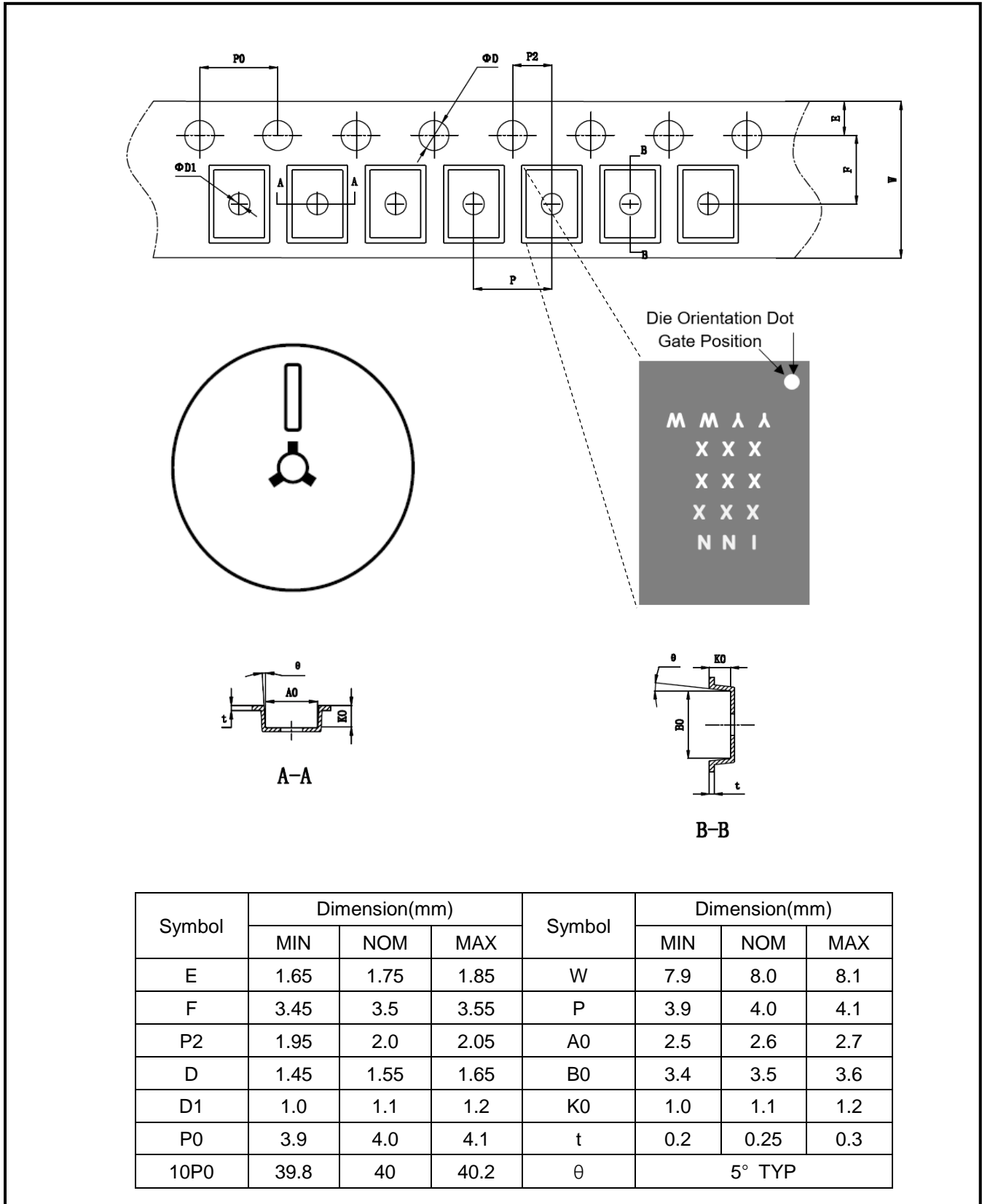


### Marking Reference:



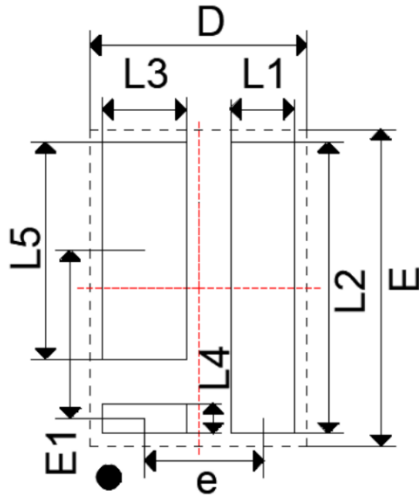
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Marking Line 2 (XXX)	Product code
Marking Line 3 (XXX)	Lot Code
Marking Line 4 (XXX)	
Marking Line 5 (YYWW)	Date code

### 11. Reel information



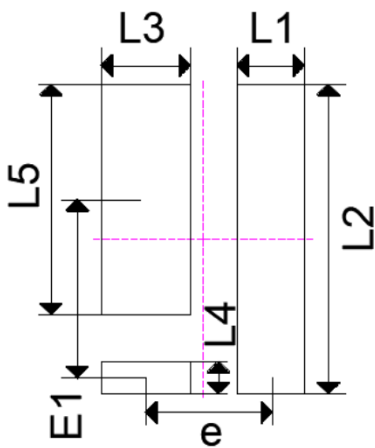
## 12. Land Pattern

### Recommended land pattern



Symbol	Millimeter	Note
D	2.2	
E	3.2	
E1	1.695	
e	1.195	2X
L1	0.64	
L2	2.94	
L3	0.85	2X
L4	0.3	
L5	2.19	

### Recommended Stencil drawing



Symbol	Millimeter	Note
E1	1.695	
e	1.195	2X
L1	0.64	
L2	2.94	
L3	0.85	2X
L4	0.3	
L5	2.19	

## 13. Revision history

### Major changes since the last revision

Revision	Date	Description of changes
1.0	2022-05-05	Rev 1.0 version release
1.1	2023-11-29	Update Pin information& Electric characteristics & diagrams
1.2	2025-02-19	Add Land Pattern

## Important Notice

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